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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/749,648	12/30/2003	Sung Mun Jung	20063/10019	9406	
34431	7590 07/15/2005		EXAM	INER	
HANLEY, FLIGHT & ZIMMERMAN, LLC			CHACKO DAV	CHACKO DAVIS, DABORAH	
20 N. WACKI SUITE 4220	ER DRIVE		ART UNIT	PAPER NUMBER	
CHICAGO, II	CHICAGO, IL 60606				
			DATE MAILED: 07/15/2005	· ·	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)
	10/749,648	JUNG ET AL.
Office Action Summary	Examiner	Art Unit
	Daborah Chacko-Davis	1756
The MAILING DATE of this communication ap	opears on the cover sheet with the	e correspondence address
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory period. - Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mailine earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be ply within the statutory minimum of thirty (30) of d will apply and will expire SIX (6) MONTHS for tte, cause the application to become ABANDO	timely filed days will be considered timely. om the mailing date of this communication. NED (35 U.S.C. § 133).
Status		
1) ☐ Responsive to communication(s) filed on 30 and 2a) ☐ This action is FINAL . 2b) ☐ This action is application is in condition for allowed closed in accordance with the practice under	is action is non-final. ance except for formal matters, p	
Disposition of Claims		
4) ☐ Claim(s) 1-9 is/are pending in the application 4a) Of the above claim(s) is/are withdres 5) ☐ Claim(s) 3-6 is/are allowed. 6) ☐ Claim(s) 1-2, and 7-9 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/	awn from consideration.	
Application Papers		
9) The specification is objected to by the Examir	ner.	
	cepted or b) objected to by th	e Examiner.
Applicant may not request that any objection to the		
Replacement drawing sheet(s) including the correctable. 11) The oath or declaration is objected to by the E		·
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for foreig a) All b) Some * c) None of: 1. Certified copies of the priority documer 2. Certified copies of the priority documer 3. Copies of the certified copies of the pri application from the International Bures * See the attached detailed Office action for a list	nts have been received. Ints have been received in Applic It ority documents have been rece It au (PCT Rule 17.2(a)).	ation No ived in this National Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date 03/04.	6) Other:	Date al Patent Application (PTO-152)
PTOL-326 (Rev. 1-04) Office A	Action Summary	Part of Paper No./Mail Date 0625

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claims 1-2, and 7-9, are rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 6,596,608 (Saito).

Saito, in col 8, lines 1-30, and lines 57-64, in col 9, lines 1-28, and in col 10, lines 16-19, discloses a memory device comprising a memory cell region (on a substrate) including a gate, a source diffusion region, a drain diffusion region, a device isolation region; and a peripheral region adjacent the memory cell region, that includes a peripheral circuit region, a device isolation region, wherein the trench formed in the peripheral region is deeper than the trenches formed in the memory cell region (claim 1). Saito, in col 13, lines 8-10, and lines 50-51, discloses that the trenches in the cell region possess a depth of about 200nm (claim 2). Saito, in col 8, lines 1-30, and lines 57-64, in col 9, lines 1-28, in col 11, lines 18-67, in col 12, lines 1-43, , in col 15, lines 32-35, discloses a method of forming a memory device comprising forming i) a memory cell region, ii) a peripheral region that includes a peripheral circuit region on a silicon substrate, iii) implanting As ions into the memory cell region to form diffusion regions

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(inherently possesses the claimed implantation energy), iv) forming a pad oxide (silicon oxide) film on the substrate, v) forming a silicon nitride (pad nitride) on the pad oxide, forming a resist pattern on the pad nitride film (reference 7 of figure 5A), vi) etching part of the pad nitride film, pad oxide film and the substrate using the photoresist pattern as the mask (see figures 6A, 6D, and 7A), wherein etching the silicon nitride using an etchant with high selectivity of the pad nitride to the pad oxide, etching the silicon oxide selectively (not etching the silicon substrate), and etching the silicon substrate in the peripheral region selectively (not etching the oxide in the cell region) (claims 1-2, and 7-9).

Allowable Subject Matter

3. Claims 3-6, are allowable over the prior art of record (U. S. Patent No. 6,596,608 (Saito) because the prior art of record does not disclose performing an etching process using the etched pad nitride layer as a mask so that a relatively shallow trench area is formed in the cell region, and a relatively deep trench in formed in the peripheral region.

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Daborah Chacko-Davis whose telephone number is (571) 272-1380. The examiner can normally be reached on M-F 9:30 - 6:00. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Mark F Huff can be reached on (571) 272-1385. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

dcd

June 25, 2004.

JOHN A. MCPHERSON PRIMARY EXAMINES